

CLAIMS

WHAT IS CLAIMED IS:

1. An image sensor package, comprising:

5 a substrate including plural metal sheets, which are spaced apart and arranged in an alternating manner, each of the metal sheets including a first board and a second board positioned at different heights, the thicken of the outside ends of the first board being smaller than the inside ends of the first board, a encapsulate layer being encapsulated the plural metal sheets to form a upper surface and a lower surface, so that the outside ends of the first board and the
10 second board are exposed from the encapsulate layer;

a frame layer formed around and under the substrate to form a cavity with the substrate;

a photosensitive chip positioned on upper surface of the substrate and within the cavity;

15 a plurality of wires electrically connecting the outside ends of the first boards to the photosensitive chip; and

a transparent layer placed on the frame layer to cover the photosensitive chip.

2. The image sensor package according to claim 1, wherein the frame layer
20 and the encapsulate layer are made of a thermal plastic material by way of injection molding.

3. The image sensor package according to claim 1, wherein the substrate further comprises a middle board, which are arranged in a zone enclosed by the metal sheets and apart from the metal sheets, and the photosensitive chip is placed on the middle board.

- 5 4. The image sensor package according to claim 1, wherein the each of outside ends of the first board of the metal sheets can be manufactured by way of pressing.